

SMILE microLED platforms as customer-centric display solutions

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Founded 2019

The difference:

We:

Big Players do no touch their standard processes and

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often do not think outside their box

45+ person years of development

Passionate TEAM of ~15 employees

We understand the InGaN material system

• We are safe to provide any design from 1 ... 1000 µm!

Unique technology to process GaN material system

 Customers receive their <u>customized</u> microLED solution even in small quantities within short lead times

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Monolithic approach: SMILE Platforms

- System with 16 x 16 pixels
- Standardized contact ring for different pixel sizes & pitches & wavelengths.
- 170 kHz frame rate



- System with 8 x 8 pixels
- Standardized contact ring for different pixel sizes & pitches & wavelengths.



5 µm pixel size 5 µm distance.

Single pixel modulated with 1kHz in this video.

Too fast for camera.



From UV to green of course...

SMILE Platforms – Tuneable native red InGaN



 Red microLEDs with feature sizes down to 3 µm.

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- Tuneable
- Can be adapted to customer designs with several emitters on a chip or distinct microLEDs on wafer







100µm

Example: Information displays



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Our general take on "assembled" displays



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Transfer of µLEDs

Best LED process is nothing without proper transfer tools.



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Example 4K Display: 3840 x 2160 (pixels) x 3 (RGB) = 24.88 million microLEDs. 99,99% successful transfers → Still 2489 dead pixels...

We perform and offer

- LLO after bonding or
- LIFT for direct µLED transfer+bond

Towards standardization of µLED-dies

Potential size of

- Die 14 // 20 // 40 // 80 // + μm
- Contact pad 5 ... 40 µm any shape
- Emitter
 2 ... 75+ μm



Dies with size 80 x 80 μ m² with different contact pads. Ready for transfer.

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No "golden way" yet in the microLED industry. Standards regarding die sizes, contacts, and emitters have huge benefits at the interfaces of all industry players.



Towards standardization of µLED-dies





Die size 14 x 14 μ m².

Towards standardization of µLED-dies





Die size 14 x 14 μ m².



We deliver your µLEDs GaN-on-Sapphire

Proposed standard die geometry:

- Die
 - 10 x 10
 - 20 x 20
 - 40 x 40 µm
- Pad size:
 - margin 1/10 of die size
 - spacing 2/10 of die size
- Emitter
 - 8/10 of die size (die size dependent)

... and perform the transfer with our toolbox.





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